

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ANUBHAV SRIVASTAVA	02/13/2020
SANKARAN KESAVAN	02/13/2020
PARAG VAISHANVA	02/13/2020
RECEIVING PARTY DATA	
Name:	SONY CORPORATION
Street Address:	1-7-1 KONAN
Internal Address:	MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1080075
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16869892
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	CHIP LAW GROUP
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Address Line 4:	CHICAGO, ILLINOIS 60611
ATTORNEY DOCKET NUMBER:	201806029.02
NAME OF SUBMITTER:	PRAMOD CHINTALAPOODI
SIGNATURE:	/Pramod Chintalapoodi/
DATE SIGNED:	05/08/2020
Total Attachments: 2	
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source=20180602902_Assignment#page2.tif	

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a joint inventor of certain new and useful improvements in **“PREDICTION OF FILM SUCCESS-QUOTIENT”**; for which application for Letters Patent of the United States of America was executed by us on the date indicated next to our name;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075, Japan (hereinafter referenced as ASSIGNEE(S)) is desirous of securing all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, in return for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and any foreign countries, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America or any foreign country adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and foreign countries, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and foreign countries;

I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at their own expense;

I further agree that ASSIGNEES will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with or impact in any way this assignment and sale;

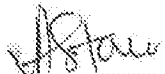
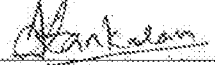
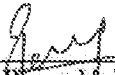
I further agree that this Assignment shall be deemed to have been made and executed in the State of Delaware and any dispute arising hereunder not governed by US federal law will be resolved in accordance with the laws of the State of Delaware without reference to its conflict of law principles. I hereby consent and submit to the jurisdiction of the federal and state courts located in the State of Delaware. Any action or suit under this Agreement or otherwise arising from the relationship between the parties will only be brought in any federal or state court with appropriate jurisdiction over the subject matter hereof sitting in the State of Delaware. I WILL NOT RAISE IN CONNECTION HERewith, AND HEREBY WAIVE, TRIAL BY JURY AND/OR ANY DEFENSES BASED UPON THE VENUE, THE INCONVENIENCE OF THE FORUM, THE LACK OF PERSONAL JURISDICTION, THE SUFFICIENCY OF SERVICE OF PROCESS OR THE LIKE IN ANY ACTION OR SUIT ARISING FROM SUCH DISPUTE;

I agree that all my obligations hereunder shall survive any termination of my employment and shall be binding on my heirs, executors, administrators, or other legal representatives or assigns;

Docket No. 201806029.02

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this document in the spaces that follow: Serial Number: 16/869,892
Filing Date: May 8, 2020

This assignment is executed on the date indicated below.

 Anubhav Srivastava	Dated: <u>13/02/2020</u>
 Sankaran Kesavan	Dated: <u>13/02/2020</u>
 Parag Maishanva	Dated: <u>13/02/2020</u>